

Power Supply Design Seminar

Introduction to the trans-inductor voltage regulator (TLVR)

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Agenda/overview

- Background and motivation
- Transinductor voltage regulator (TLVR) topology introduction
- Practical considerations
- Conclusion



Voltage regulator design challenges

- Silicon technology continues to shrink (but this is slowing)
 3-nm digital → lower
- Application-specific integrated circuit (ASIC) operating voltages remain 0.7 V to 1.0 V (up to 1.8 V)
- High-core-count designs and chiplet revolution driving rapid increase in operating currents >1,000-A designs
- Extreme load transient requirements 1,000 A/µs, ±3%





Motivation for TLVR: Improving transient response



Motivation for TLVR: Improving transient response



Buck converter vs. TLVR topology



- **Buck-derived** topology optimized for fast transient response
- TLVR is a new twist on the coupledinductor buck converter
- When it makes sense:
 - High phase count (>six phases)
 - High di/dt load transient
 - Moderate voltage ripple

Traditional coupled inductor

 Φ_1 Φ_2 Φ_2 Φ_2 Φ_2 Φ_2 Φ_3 Φ_4 Φ_4 Φ_2 Φ_3 Φ_4 Φ_4

Traditional coupled inductor (two phase)

Multiple windings share a single core

- Typical coupling coefficient: ≈0.5 to 0.7
- Higher power density
- Customized design for phase count/layouts

Difficult to extend to higher phases



- Challenge: Symmetry is required for equal coupling among phases
- Challenge: Complex geometry required to maintain symmetry at higher phase counts

Coupling allows high steady state inductance (low ripple) and low transient inductance (fast transient)



Indirect-coupled inductor

Indirect-coupled inductor (two phase)



TLVR: Indirect-coupling and compensating inductor (L_c)



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- Phases are coupled symmetrically without a sharing core
- Simple core geometry, scalable solution
- Challenging to control coupling

TLVR topology overview



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TLVR operating principle: Steady state

Phase current

description (I_{PRI4})

This phase (SW4)

is on; all others are

I_{I M4} increases

2. All phases are off

 I_{LC} decreases

I_{IM} decreases

 I_{LC} increases

I_{I M4} decreases

This phase (SW4)

 I_{LC} increases

1.

3.

on

off



TLVR steady-state operation (four-phase example, no overlap)





TLVR operating principle: Transient step-up





TLVR operating principle: Transient step-down





Side-by-side comparison: Load step-up





Side-by-side comparison: Load step-down





DC load line further reduces output capacitance

DC load-line (DCLL) behavior is identical between buck and TLVR designs





L_c as an AC inductor – I_{LC} during a transient



High-frequency transient (65 kHz)





VR vs. TLVR efficiency comparison ($L_{BUCK} = L_M = L_C$)





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Dynamic phase shedding





Example side-by-side design

| Parameter | TLVR | Multiphase buck |
|-----------------------------------|-------------------------------------|------------------|
| Controller/SPS | TPS53689, CSD95440 | |
| V _{IN} | 12 V | |
| V _{OUT} | 1.8 V | |
| Number of phases | 8 phases | |
| Switching frequency | 900 kHz | |
| Load step | 60 A-430 A, 1,000 A/µs, 1 kHz-1 MHz | |
| Load line | 0.5 mΩ | |
| L _m /L _{buck} | 150 nH | 70 nH |
| L _c | 100 nH | - |
| C _{bulk} (polymer) | 0 × 470 μF | 5 × 470 µF |
| Multilayer ceramic capacitors | 80 × 22 µF 0402 | 80 × 22 μF 0402 |
| | 56 × 47 µF 0603 | 45 × 47 μF 0805 |
| | 0 × 100 µF 0805 | 15 × 100 μF 0805 |
| | 8 × 0.1 μF 0402 | 8 × 0.1 μF 0402 |
| Total C _{out} | 4.4 mF | 7.7 mF |

More transient margin with 45% reduction in output capacitance required



Practical considerations



L_c inductor selection

- Typically select L_c between L_m and 1.25 $\,\times\,$ L_m
- Minimal root-mean-square current (RMS) required

 $I_{\rm rms(L_c)} \approx \frac{\Delta I_{\rm Lc}}{\sqrt{12}}$

• High saturation current required

 $I_{sat} \gg t_{resp} \times \left[\frac{N_{on(step)} \times V_{IN} - N_{total} \times V_{OUT}}{L_c} \right]$

- Voltage across L_c can be $\gg V_{IN}$

 $V_{LC(max)} = N_{on(step)} \times V_{IN} - N_{total} \times V_{OUT}$

Example L_c selection

| Parameter | Value |
|-----------------------------|----------------------------|
| V _{IN} | 12 V |
| V _{OUT} | 0.8 V |
| F _{sw} | 600 kHz |
| N _{total} | 8 phases |
| L _m | 150 nH |
| L _c | 180 nH |
| Load transient | 50-500 A, 1,000 A/µs |
| ΔI_{Lc} | 5.0 A |
| F _{LC} | 4.8 MHz |
| I _{RMS(Lc)} | 2.8 A |
| Margin for I _{SAT} | 25% |
| I _{SAT(min)} | 75 A |
| $\Delta V_{Lc(max)}$ | 30 V ($N_{OVERLAP} = 3$) |



Output-ripple cancellation



Reduced ripple voltage: Interleaved TLVR



- For high-phase-count (>12 phase) designs, creating two (or more) L_c loops achieves interleaving
- May also be advantageous for layout and electromagnetic interference (EMI) concerns (reduced L_c frequency, reduced maximum L_c voltage)



Typical power-stage layout

Interleaving phase fire order reduces crosstalk
and reduces input capacitor stress

- L_c current still carries high current in a transient
- Recommend ≈50 mils



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Printed circuit board layout: Multiside power delivery



Example:

- 32-phase design
- Two L_c interleaved design

Recommendations:

- Symmetrical power train and L_c layout
- Decoupling and current-resistance (IR) drop on input traces
- PWM pin trace capacitance
 - Controller PWM drive strength
- Current-sense trace capacitance
 - Low-pass filter effect for current monitor (Imon) signals



TLVR-optimized controllers and power stages

TLVR-optimized power stages



High bandwidth, real current information reporting

| Part number | Current rating | Package/features |
|-------------|--------------------------------|----------------------------|
| CSD95440 | 80-A peak, 40 A _{RMS} | 5 mm × 6 mm (voltage Imon) |
| CSD95510 | 90-A peak, 50 A _{RMS} | 4 mm × 6 mm (voltage Imon) |
| CSD95560 | 90-A peak, 50 A _{RMS} | 4 mm × 6 mm (current Imon) |
| CSD95520 | 60-A peak, 30 A _{RMS} | 4 mm × 5 mm (voltage Imon) |
| CSD95570 | 60-A peak, 30 A _{RMS} | 4 mm × 5 mm (current Imon) |

TLVR-optimized controllers



Load transient detection based on PWM timing

| Part number | Phases | Package/features |
|-------------|--------|-----------------------------|
| TPS53685 | 8 | 5 mm × 5 mm AMD interface |
| TPS536C5 | 12 | 6 mm × 6 mm AMD interface |
| TPS53689T | 8 | 5 mm × 5 mm Intel interface |
| TPS536C9T | 12 | 6 mm × 6 mm Intel interface |

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Conclusion



Summary

- Introduced the TLVR topology
 - Buck-derived topology similar to coupled inductors for high-phase-count designs
 - Better modularity and reuse for TLVR, since inductors do not share a core
 - Significant output capacitor savings given coupled-inductor behavior
- Practical considerations for TLVR designs
 - TLVR designs typically have higher ripple current and voltage vs. buck
 - Interleaving for high-phase-count designs
 - Printed circuit board layout for TLVR designs is similar to buck, with $\rm L_{c}$ loop added
- TLVR-optimized components
 - High-bandwidth and system-level optimizations needed to optimize for TLVR designs



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